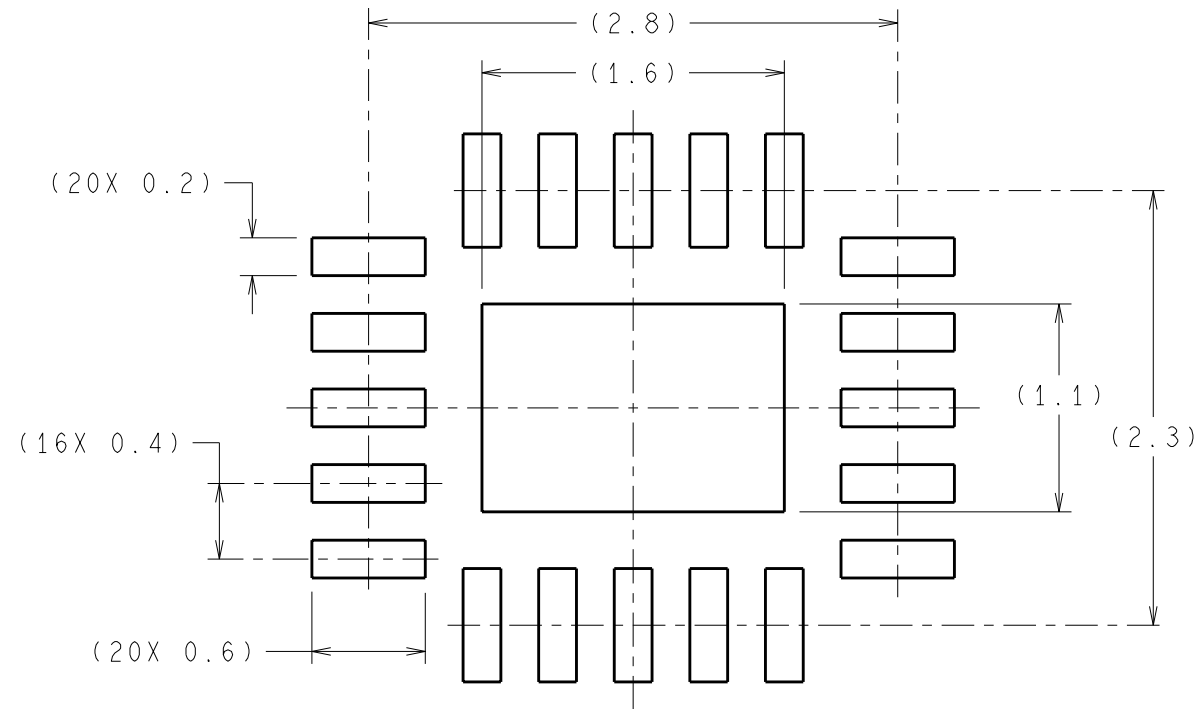
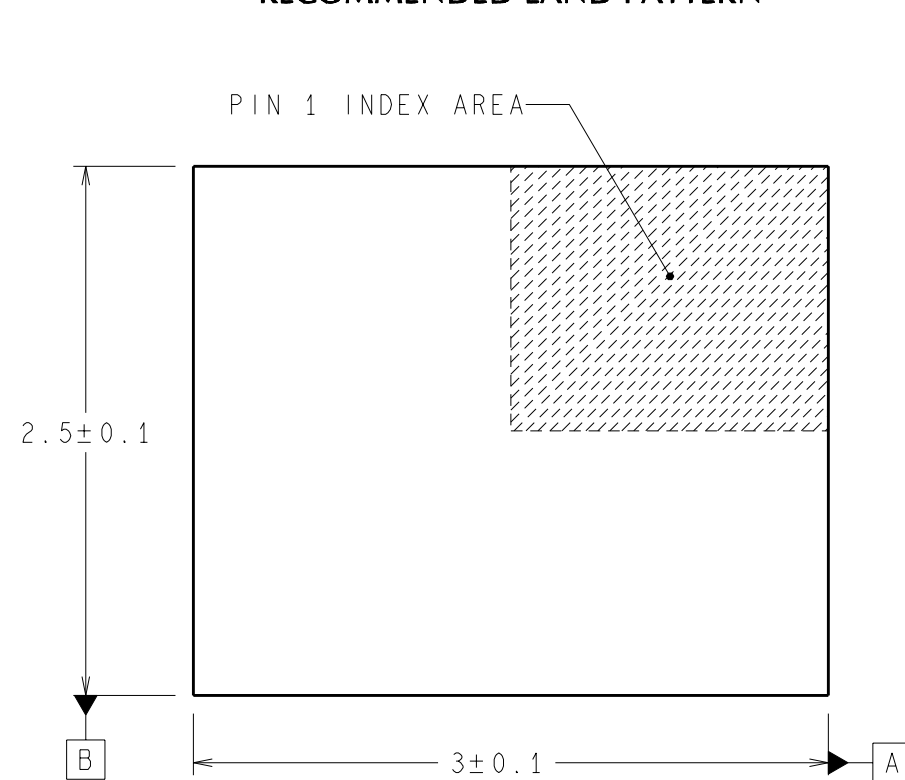


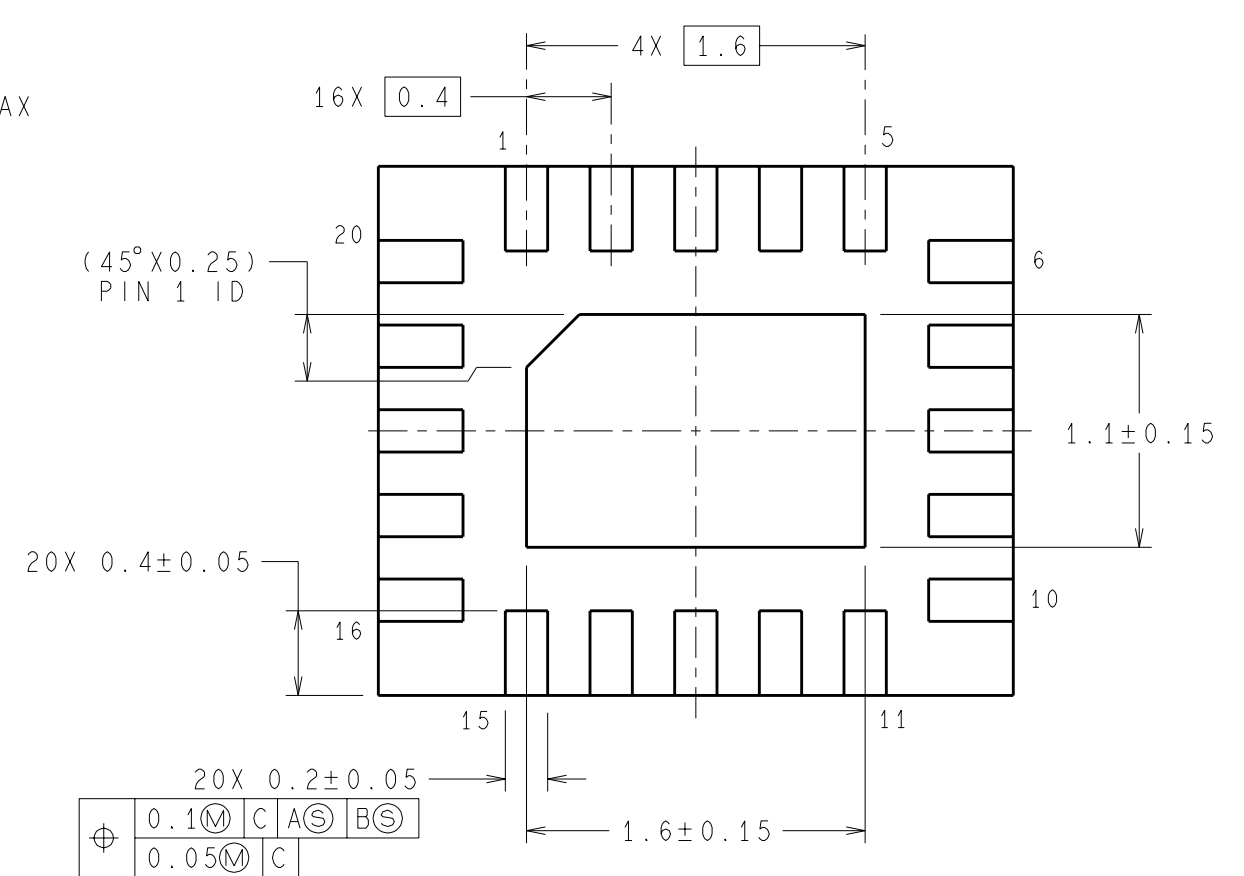
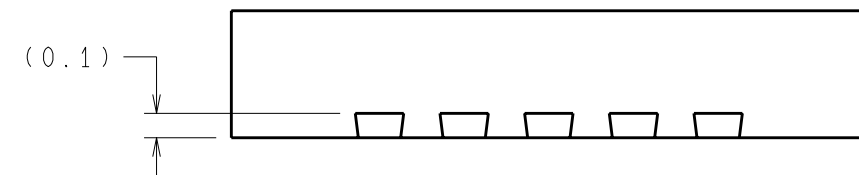
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2279	04/20/2007	TL/RW
B	LD LENGTH WAS 0.35; EXP PAD WAS 1.8 X 1.3; REVISE LAND PATTERN ACCORDINGLY; UPDATE NOTE 3	2307	05/31/2007	TL/RW



RECOMMENDED LAND PATTERN



DIMENSIONS ARE IN MILLIMETERS  
DIMENSIONS IN ( ) FOR REFERENCE ONLY



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
- NO JEDEC REGISTRATION AS OF MAY 2007.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	T. LEQUANG	04/20/2007	
DFTG. CHK.	MARTA SUCHY	05/31/2007	
ENGR. CHK.	RANDY WALBERG	05/31/2007	
PROJECTION:  MM			SCALE: NTS SIZE: B DRAWING NUMBER: (SC)MKT-SPF20A REV: B
FORMERLY: X-02077			SHEET 1 of 1